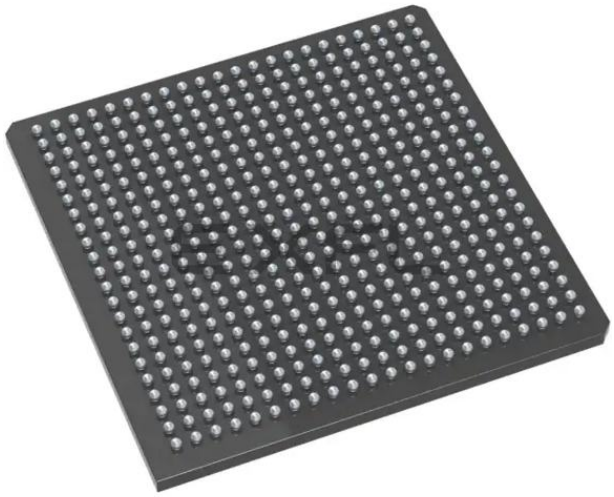

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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	8064
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	317
Number of Gates	500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	484-BGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax500-fg484m

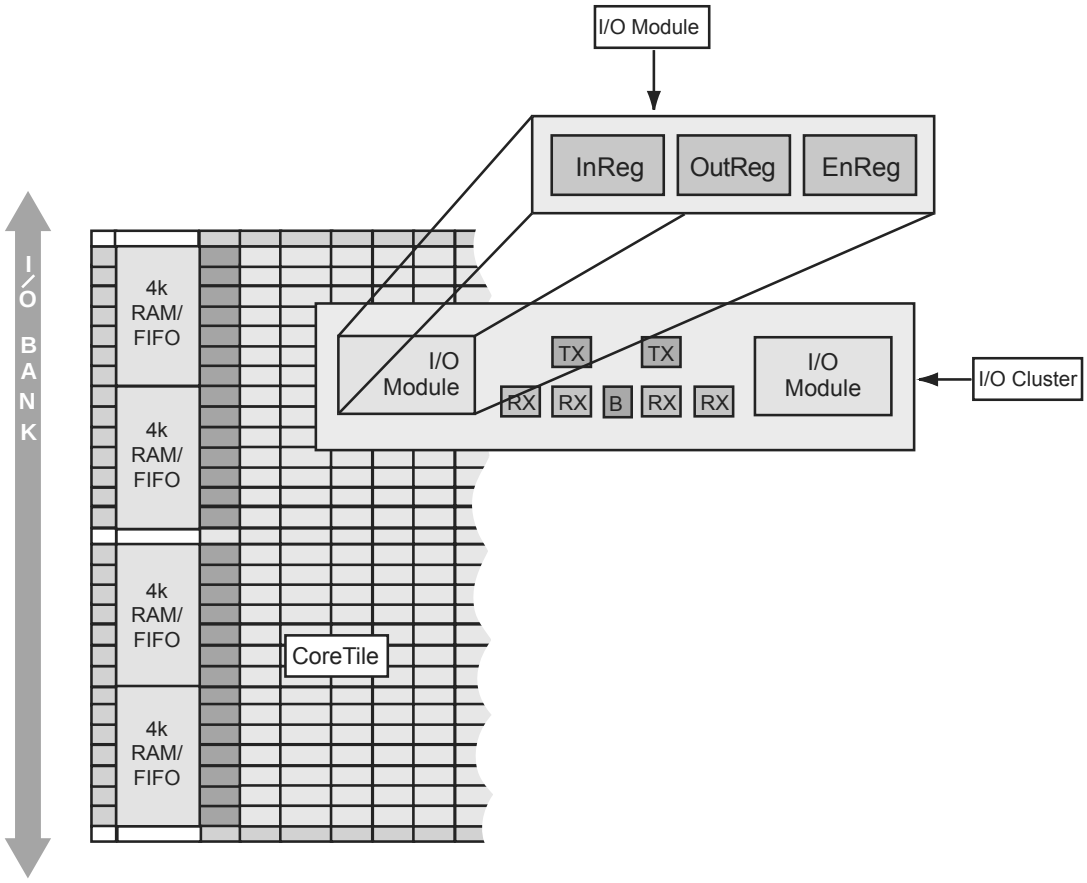


Figure 1-7 • **I/O Cluster Arrangement**

Routing

The AX hierarchical routing structure ties the logic modules, the embedded memory blocks, and the I/O modules together (Figure 1-8 on page 1-6). At the lowest level, in and between SuperClusters, there are three local routing structures: FastConnect, DirectConnect, and CarryConnect routing. DirectConnects provide the highest performance routing inside the SuperClusters by connecting a C-cell to the adjacent R-cell. DirectConnects do not require an antifuse to make the connection and achieve a signal propagation time of less than 0.1 ns.

FastConnects provide high-performance, horizontal routing inside the SuperCluster and vertical routing to the SuperCluster immediately below it. Only one programmable connection is used in a FastConnect path, delivering a maximum routing delay of 0.4 ns.

CarryConnects are used for routing carry logic between adjacent SuperClusters. They connect the FCO output of one two-bit, C-cell carry logic to the FCI input of the two-bit, C-cell carry logic of the SuperCluster below it. CarryConnects do not require an antifuse to make the connection and achieve a signal propagation time of less than 0.1 ns.

The next level contains the core tile routing. Over the SuperClusters within a core tile, both vertical and horizontal tracks run across rows or columns, respectively. At the chip level, vertical and horizontal tracks extend across the full length of the device, both north-to-south and east-to-west. These tracks are composed of highway routing that extend the entire length of the device (segmented at core tile boundaries) as well as segmented routing of varying lengths.

Table 2-4 • **Default CLOAD/VCCI**

	C_{LOAD} (pF)	VCCI (V)	PLOAD (mw/MHz)	P10 (mw/MHz)	PI/O (mW/MHz)*
Single-Ended without VREF					
LVTTL 24 mA High Slew	35	3.3	381.2	267.5	648.7
LVTTL 16 mA High Slew	35	3.3	381.2	225.1	606.3
LVTTL 12 mA High Slew	35	3.3	381.2	165.9	547.1
LVTTL 8 mA High Slew	35	3.3	381.2	130.3	511.5
LVTTL 24 mA Low Slew	35	3.3	381.2	169.2	550.4
LVTTL 16 mA Low Slew	35	3.3	381.2	150.8	532.0
LVTTL 12 mA Low Slew	35	3.3	381.2	138.6	519.8
LVTTL 8 mA Low Slew	35	3.3	381.2	118.7	499.9
LVCMOS – 25	35	2.5	218.8	148.0	366.8
LVCMOS – 18	35	1.8	113.4	73.4	186.8
LVCMOS – 15 (JESD8-11)	35	1.5	78.8	49.5	128.3
PCI	10	3.3	108.9	218.5	327.4
PCI-X	10	3.3	108.9	162.9	271.8
Single-Ended with VREF					
HSTL-I	20	1.5	–	40.9	40.9
SSTL2-I	30	2.5	–	171.2	171.2
SSTL2-II	30	2.5	–	147.8	147.8
SSTL3-I	30	3.3	–	327.2	327.2
SSTL3-II	30	3.3	–	288.4	288.4
GTLP – 25	10	2.5	–	61.5	61.5
GTLP – 33	10	3.3	–	68.5	68.5
Differential					
LVPECL – 33	N/A	3.3	–	260.6	260.6
LVDS – 25	N/A	2.5	–	145.8	145.8

Note: $*P_{I/O} = P10 + C_{LOAD} * VCC_I^2$

5 V Tolerance

There are two schemes to achieve 5 V tolerance:

1. 3.3 V PCI and 3.3 V PCI-X are the only I/O standards that directly allow 5 V tolerance. To implement this, an internal clamp diode between the input pad and the VCCI pad is enabled so that the voltage at the input pin is clamped, as shown in EQ 3:

Vinput = VCCI + Vdiode = 3.3 V + 0.7 V = 4.0 V

EQ 3

The internal VCCI clamp diode is only enabled while the device is powered on, so the voltage at the input will not be clamped if the VCCI or VCCA are powered off. An external series resistor (~100 Ω) is required between the input pin and the 5 V signal source to limit the current to less than 20 mA (Figure 2-3). The 100 Ω resistor was chosen to meet the input Tr/Tf requirement (Table 2-19 on page 2-21). The GND clamp diode is available for all I/O standards and always enabled.

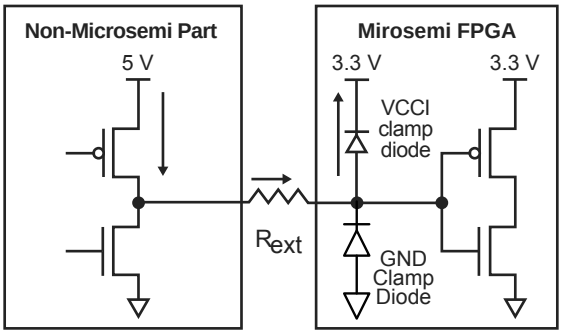


Figure 2-3 • **Use of an External Resistor for 5 V Tolerance**

2. 5 V tolerance can also be achieved with 3.3 V I/O standards (3.3 V PCI, 3.3 V PCI-X, and LVTTL) using a bus-switch product (e.g. IDTQS32X2384). This will convert the 5 V signal to a 3.3 V signal with minimum delay (Figure 2-4).

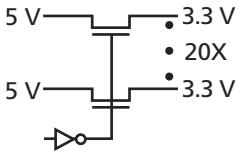


Figure 2-4 • **Bus Switch IDTQS32X2384**

Simultaneous Switching Outputs (SSO)

When multiple output drivers switch simultaneously, they induce a voltage drop in the chip/package power distribution. This simultaneous switching momentarily raises the ground voltage within the device relative to the system ground. This apparent shift in the ground potential to a non-zero value is known as simultaneous switching noise (SSN) or more commonly, ground bounce.

SSN becomes more of an issue in high pin count packages and when using high performance devices such as the Axcelerator family. Based upon testing, Microsemi recommends that users not exceed eight simultaneous switching outputs (SSO) per each VCCI/GND pair. To ease this potential burden on designers, Microsemi has designed all of the Axcelerator BGAs[3] to not exceed this limit with the exception of the CS180, which has an I/O to VCCI/GND pair ratio of nine to one.

Please refer to the *Simultaneous Switching Noise and Signal Integrity* application note for more information.

3. The user should note that in Bank 8 of both AX1000-FG484 and AX500-FG484, there are local violations of this 8:1 ratio.

1.8 V LVCMOS

Low-Voltage Complementary Metal-Oxide Semiconductor for 1.8 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.8 V applications. It uses a 3.3 V tolerant CMOS input buffer and a push-pull output buffer.

***Table 2-26* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
–0.3	0.2 VCCI	0.7 VCCI	3.6	0.2	VCCI – 0.2	8 mA	–8 mA

AC Loadings

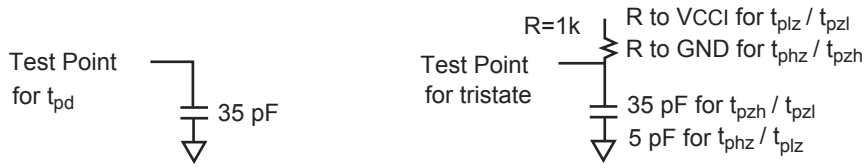


***Figure 2-17* • AC Test Loads**

***Table 2-27* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
0	1.8	0.5 VCCI	N/A	35

*Note: * Measuring Point = VTRIP*

Timing Characteristics

***Table 2-32* • 1.5V LVCMOS I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.4 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS15 (JESD8-11) I/O Module Timing								
t_{DP}	Input Buffer		3.59		4.09		4.81	ns
t_{PY}	Output Buffer		6.05		6.89		8.10	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.31		3.34		3.34	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		4.56		4.58		4.59	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.37		7.25		8.52	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.94		7.90		9.29	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Voltage-Referenced I/O Standards

GTL+

Gunning Transceiver Logic Plus is a high-speed bus standard (JESD8-3). It requires a differential amplifier input buffer and an Open Drain output buffer. The VCCI pin should be connected to 2.5 V or 3.3 V. Note that 2.5 V GTL+ is not supported across the full military temperature range.

***Table 2-37* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
N/A	VREF – 0.1	VREF + 0.1	N/A	0.6	NA	NA	NA

AC Loadings

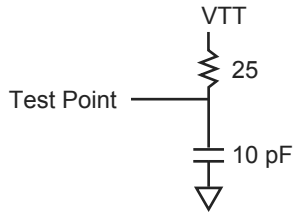


***Figure 2-19* • AC Test Loads**

***Table 2-38* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 0.2	VREF + 0.2	VREF	1.0	10

*Note: * Measuring Point = VTRIP*

Timing Characteristics

***Table 2-39* • 2.5 V GTL+ I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
2.5 V GTL+ I/O Module Timing								
t_{DP}	Input Buffer		1.71		1.95		2.29	ns
t_{PY}	Output Buffer		1.13		1.29		1.52	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Module Specifications

C-Cell

Introduction

The C-cell is one of the two logic module types in the AX architecture. It is the combinatorial logic resource in the Axcelerator device. The AX architecture implements a new combinatorial cell that is an extension of the C-cell implemented in the SX-A family. The main enhancement of the new C-cell is the addition of carry-chain logic.

The C-cell can be used in a carry-chain mode to construct arithmetic functions. If carry-chain logic is not required, it can be disabled.

The C-cell features the following (Figure 2-27):

- Eight-input MUX (data: D0-D3, select: A0, A1, B0, B1). User signals can be routed to any one of these inputs. Any of the C-cell inputs (D0-D3, A0, A1, B0, B1) can be tied to one of the four routed clocks (CLKE/F/G/H).
- Inverter (DB input) can be used to drive a complement signal of any of the inputs to the C-cell.
- A carry input and a carry output. The carry input signal of the C-cell is the carry output from the C-cell directly to the north.
- Carry connect for carry-chain logic with a signal propagation time of less than 0.1 ns.
- A hardwired connection (direct connect) to the adjacent R-cell (Register Cell) for all C-cells on the east side of a SuperCluster with a signal propagation time of less than 0.1 ns.

This layout of the C-cell (and the C-cell Cluster) enables the implementation of over 4,000 functions of up to five bits. For example, two C-cells can be used together to implement a four-input XOR function in a single cell delay.

The carry-chain configuration is handled automatically for the user with Microsemi's extensive macro library (please see the *Antifuse Macro Library Guide* for a complete listing of available Axcelerator macros).

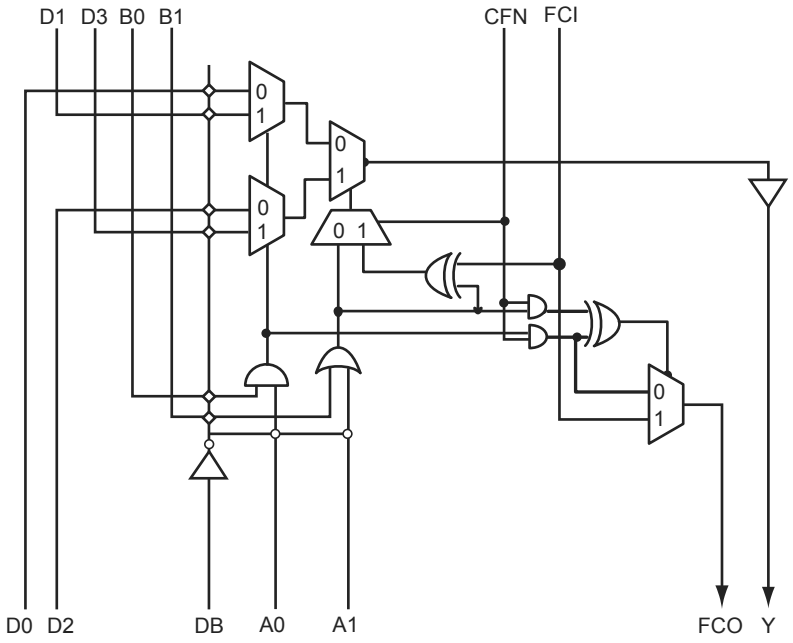
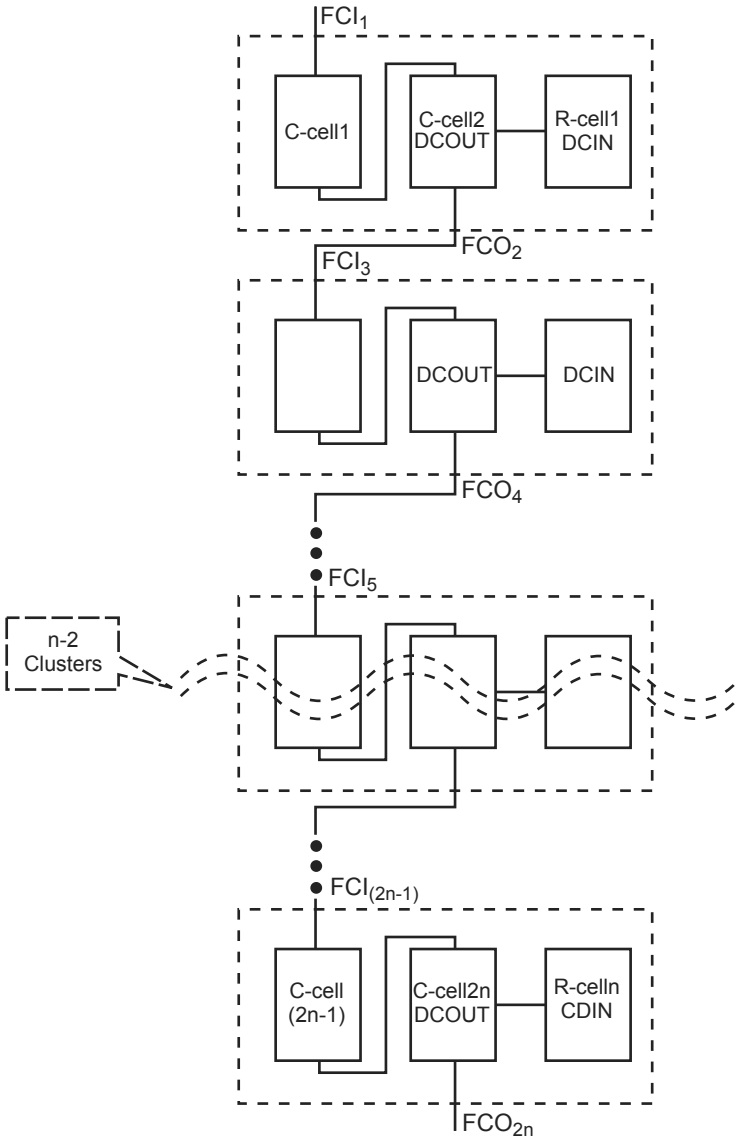


Figure 2-27 • **C-Cell**



Note: The carry-chain sequence can end on either C-cell.

Figure 2-30 • **Carry-Chain Sequencing of C-Cells**

Timing Characteristics

Refer to Table 2-62 on page 2-55 for more information on carry-chain timing.

Timing Models and Waveforms

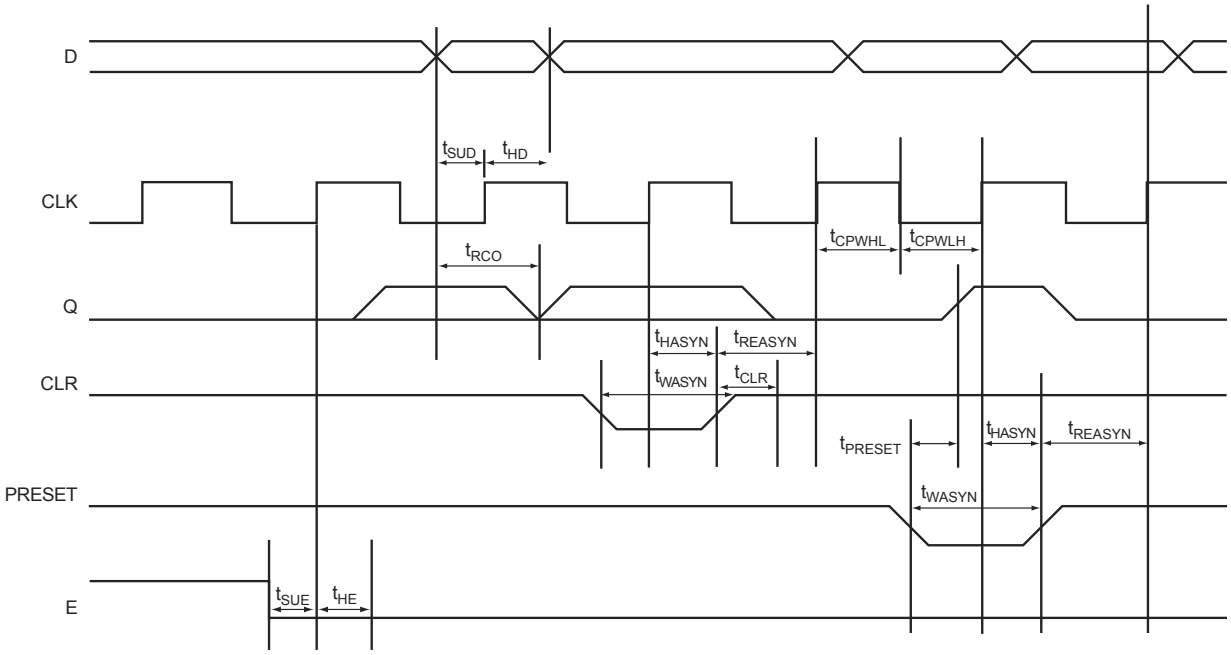


Figure 2-32 • **R-Cell Delays**

Timing Characteristics

Table 2-63 • **R-Cell**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
R-Cell Propagation Delays								
t_{RCO}	Sequential Clock-to-Q		0.67		0.77		0.90	ns
t_{CLR}	Asynchronous Clear-to-Q		0.67		0.77		0.90	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.36		0.36		0.36	ns
t_{SUD}	Flip-Flop Data Input Set-Up		0.34		0.34		0.34	ns
t_{SUE}	Flip-Flop Enable Input Set-Up		0.00		0.00		0.00	ns
t_{HD}	Flip-Flop Data Input Hold		0.67		0.77		0.90	ns
t_{HE}	Flip-Flop Enable Input Hold		0.67		0.77		0.90	ns
t_{WASYN}	Asynchronous Pulse Width	0.48		0.48		0.48		ns
t_{REASYN}	Asynchronous Recovery Time		0.23		0.27		0.31	ns
t_{HASYN}	Asynchronous Removal Time		0.36		0.36		0.36	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.36		0.36		0.36		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.36		0.36		0.36		ns

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

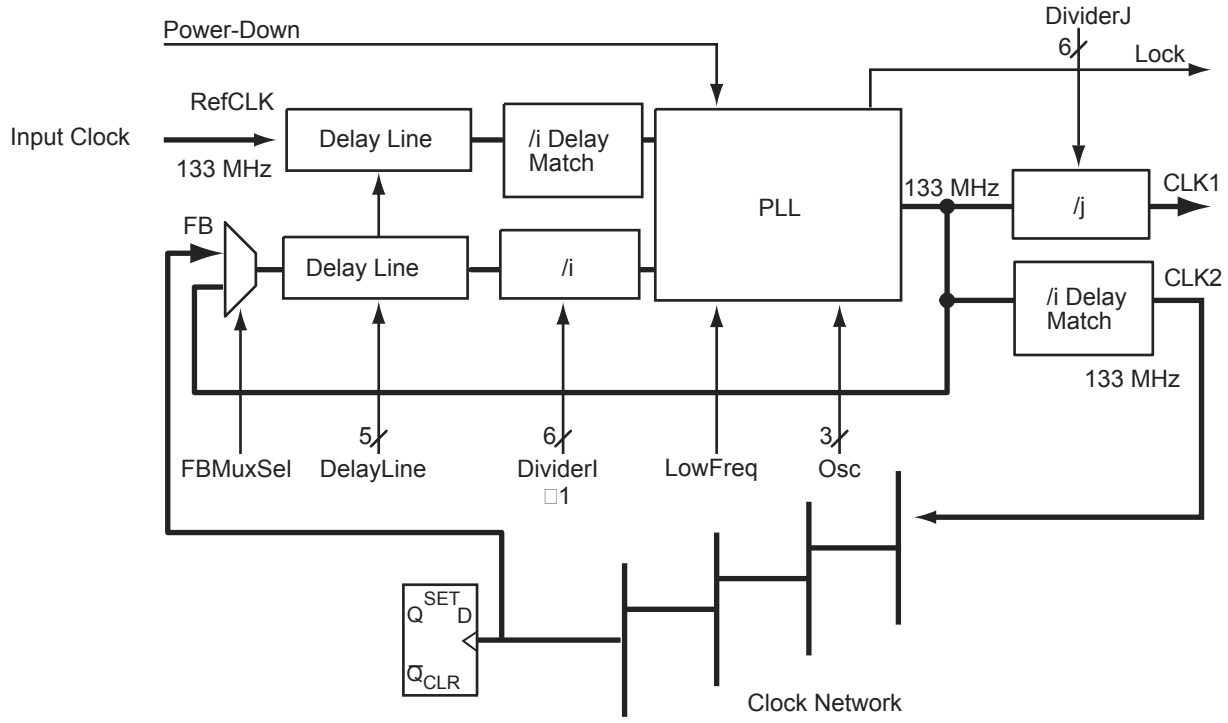


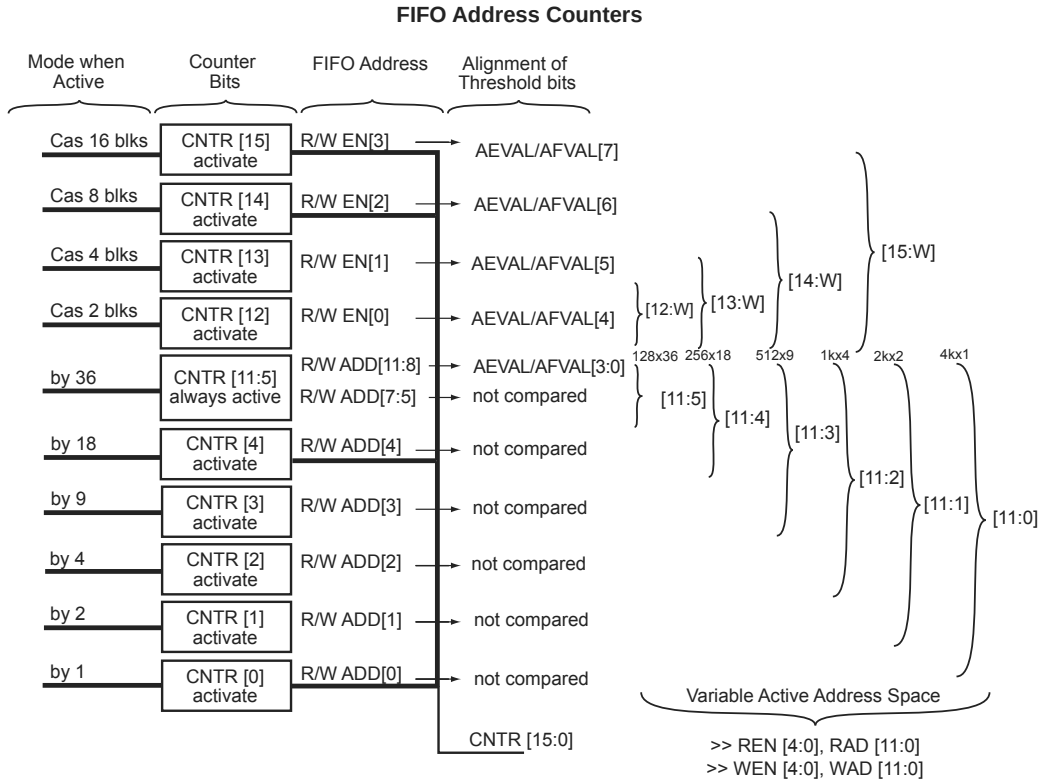
Figure 2-56 • **Using the PLL for Clock Deskewing**

FIFO Flag Logic

The FIFO is user configurable into various DEPTHs and WIDTHs. Figure 2-62 shows the FIFO address counter details.

- Bits 11 to 5 are active for all modes.
- As the data word size is reduced, more least-significant bits are added to the address.
- As the number of cascaded blocks increases, the number of significant bits in the address increases.

For example, if four blocks are cascaded as a 1kx16 FIFO with each block having a 1kx4 aspect ratio, bits 11 to 2 of the address will be used to specify locations within each RAM block, whereas bits 13 and 12 will be used to specify the RAM block.



Note: Inactive counter bits are set to zero.

Figure 2-62 • **FIFO Address Counters**

The AFULL and AEMPTY flag threshold values are programmable. The threshold values are AFVAL and AEVAL, respectively. Although the trigger threshold for each flag is defined with eight bits, the effective number of threshold bits in the comparison depends on the configuration. The effective number of threshold bits corresponds to the range of active bits in the FIFO address space (Table 2-94).

Table 2-94 • **FIFO Flag Logic**

Mode	Inactive AEVAL/AFVAL Bits	Inactive DIFF Bits (set to 0)	DIFF Comparison to AFVAL/AEVAL
Non-cascade	[7:4]	[15:12]	DIFF[11:8] withAE/FVAL[3:0]
Cascade 2 blocks	[7:5]	[15:13]	DIFF[12:8] withAE/FVAL[4:0]
Cascade 4 blocks	[7:6]	[15:14]	DIFF[13:8] withAE/FVAL[5:0]
Cascade 8 blocks	[7]	[15]	DIFF[14:8] withAE/FVAL[6:0]
Cascade 16 blocks	None	None	DIFF[15:8] withAE/FVAL[7:0]

Clock

As with RAM configuration, the RCLK and WCLK pins have independent polarity selection.

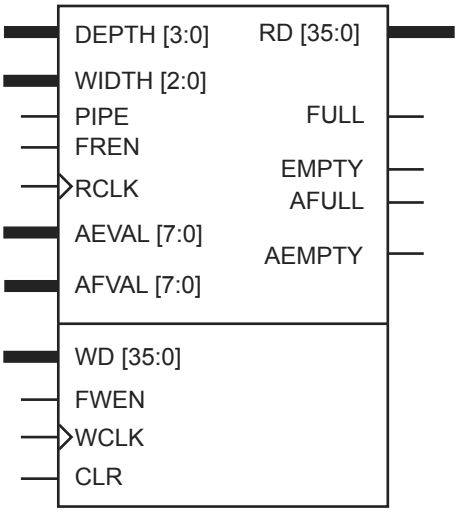


Figure 2-65 • **FIFO Block Diagram**

Table 2-97 • **FIFO Signal Description**

Signal	Direction	Description
WCLK	Input	Write clock (active either edge).
FWEN	Input	FIFO write enable. When this signal is asserted, the WD bus data is latched into the FIFO, and the internal write counters are incremented.
WD[N-1:0]	Input	Write data bus. The value N is dependent on the RAM configuration and can be 1, 2, 4, 9, 18, or 36.
FULL	Output	Active high signal indicating that the FIFO is FULL. When this signal is set, additional write requests are ignored.
AFULL	Output	Active high signal indicating that the FIFO is AFULL.
AFVAL	Input	8-bit input defining the AFULL value of the FIFO.
RCLK	Input	Read clock (active either edge).
FREN	Input	FIFO read enable.
RD[N-1:0]	Output	Read data bus. The value N is dependent on the RAM configuration and can be 1, 2, 4, 9, 18, or 36.
EMPTY	Output	Empty flag indicating that the FIFO is EMPTY. When this signal is asserted, attempts to read the FIFO will be ignored.
AEMPTY	Output	Active high signal indicating that the FIFO is AEMPTY.
AEVAL	Input	8-bit input defining the almost-empty value of the FIFO.
PIPE	Input	Sets the pipe option on or off.
CLR	Input	Active high clear input.
DEPTH	Input	Determines the depth of the FIFO and the number of FIFOs to be cascaded.
WIDTH	Input	Determines the width of the dataword/FIFO, and the number of the FIFOs to be cascaded.

***Table 2-102* • Sixteen FIFO Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		16.32		18.60		21.86	ns
t_{WHD}	Write Hold		0.00		0.00		0.00	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		13.40		13.40		13.40	ns
t_{WCKP}	Minimum WCLK Period	14.15		14.15		14.15		ns
t_{RSU}	Read Setup		17.16		19.54		22.97	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.73		0.73		0.73	ns
t_{RCKL}	RCLK Low		14.41		14.41		14.41	ns
t_{RCKP}	Minimum RCLK period	15.14		15.14		15.14		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		12.08		13.76		16.17	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Nonpipelined)		12.83		14.62		17.18	ns

Note: Timing data for these sixteen cascaded FIFO blocks uses a depth of 65,536. For all other combinations, use Microsemi's timing software.

Building RAM and FIFO Modules

RAM and FIFO modules can be generated and included in a design in two different ways:

- Using the SmartGen Core Generator where the user defines the depth and width of the FIFO/RAM, and then instantiates this block into the design (refer to the *SmartGen, FlashROM, Analog System Builder, and Flash Memory System Builder* User's Guide for more information).
- The alternative is to instantiate the RAM/FIFO blocks manually, using inverters for polarity control and tying all unused data bits to ground.

Other Architectural Features

Low Power Mode

Although designed for high performance, the AX architecture also allows the user to place the device into a low power mode. Each I/O bank in an Axcelerator device can be configured individually, when in low power mode, to tristate all outputs, disable inputs, or both. The low power mode is activated by asserting the LP pin, which is grounded in normal operation.

While in the low power mode, the device is still fully functional and all internal logic states are preserved. This allows a user to disable all but a few signals and operate the part in a low-frequency, watchdog

BG729	
AX1000 Function	Pin Number
IO109NB3F10	V24
IO109PB3F10	V25
IO110NB3F10	T20
IO110PB3F10	T21
IO111NB3F10	W26
IO111PB3F10	W27
IO112NB3F10	U22
IO112PB3F10	U23
IO113NB3F10	Y26
IO113PB3F10	Y27
IO114NB3F10	U20
IO114PB3F10	U21
IO115NB3F10	W24
IO115PB3F10	W25
IO116NB3F10	V22
IO116PB3F10	V23
IO117NB3F10	Y24
IO117PB3F10	Y25
IO118NB3F11	V20
IO118PB3F11	V21
IO119NB3F11	AA26
IO119PB3F11	AA27
IO120NB3F11	W22
IO120PB3F11	W23
IO121NB3F11	AA24
IO121PB3F11	AA25
IO122NB3F11	W20
IO122PB3F11	W21
IO123NB3F11	AB26
IO123PB3F11	AB27
IO124NB3F11	Y22
IO124PB3F11	Y23
IO125NB3F11	AB24
IO125PB3F11	AB25
IO126NB3F11	AA22
IO126PB3F11	AA23
IO127NB3F11	AC26

BG729	
AX1000 Function	Pin Number
IO127PB3F11	AC27
IO128NB3F11	Y20
IO128PB3F11	W19
Bank 4	
IO129NB4F12	AA20
IO129PB4F12	Y21
IO130NB4F12	AB22
IO130PB4F12	AB23
IO131NB4F12	AC22
IO131PB4F12	AC23
IO132NB4F12	AD23
IO132PB4F12	AD24
IO133NB4F12	AF23
IO133PB4F12	AE23
IO134NB4F12	AC21
IO134PB4F12	AB21
IO135NB4F12	AC20
IO135PB4F12	AB20
IO136NB4F12	AD21
IO136PB4F12	AD22
IO137NB4F12	Y19
IO137PB4F12	AA19
IO138NB4F12	AE21
IO138PB4F12	AE22
IO139NB4F13	AF21
IO139PB4F13	AF22
IO140NB4F13	AG22
IO140PB4F13	AG23
IO141NB4F13	Y18
IO141PB4F13	AA18
IO142NB4F13	AE20
IO142PB4F13	AD20
IO143NB4F13	AG20
IO143PB4F13	AG21
IO144NB4F13	AC19
IO144PB4F13	AB19
IO145NB4F13	AD18

BG729	
AX1000 Function	Pin Number
IO145PB4F13	AD19
IO146NB4F13	AC18
IO146PB4F13	AB18
IO147NB4F13	Y17
IO147PB4F13	AA17
IO148NB4F13	AF19
IO148PB4F13	AF20
IO149NB4F13	AC17
IO149PB4F13	AB17
IO150NB4F13	AE18
IO150PB4F13	AE19
IO151NB4F13	AA16
IO151PB4F13	Y16
IO152NB4F14	AG18
IO152PB4F14	AG19
IO153NB4F14	AC16
IO153PB4F14	AB16
IO154NB4F14	AF17
IO154PB4F14	AF18
IO155NB4F14	AB15
IO155PB4F14	AC15
IO156NB4F14	AE16
IO156PB4F14	AE17
IO157NB4F14	Y15
IO157PB4F14	AA15
IO158NB4F14	AG16
IO158PB4F14	AG17
IO159NB4F14/CLKEN	AF15
IO159PB4F14/CLKEP	AF16
IO160NB4F14/CLKFN	AD14
IO160PB4F14/CLKFP	AD15
Bank 5	
IO161NB5F15/CLKGN	AE14
IO161PB5F15/CLKGP	AE15
IO162NB5F15/CLKHN	AC13
IO162PB5F15/CLKHP	AD13
IO163NB5F15	Y14

FG1152	
AX2000 Function	Pin Number
Bank 0	
IO00NB0F0	D6
IO00PB0F0	C6
IO01NB0F0	H10
IO01PB0F0	H9
IO02NB0F0	F8
IO02PB0F0	G8
IO03NB0F0	A6
IO03PB0F0	B6
IO04NB0F0	C7
IO04PB0F0	D7
IO05NB0F0	K10
IO05PB0F0	J10
IO06NB0F0	F9
IO06PB0F0	G9
IO07NB0F0	F10
IO07PB0F0	G10
IO08NB0F0	E9
IO08PB0F0	E8
IO09NB0F0	J11
IO09PB0F0	K11
IO10NB0F0	C8
IO10PB0F0	D8
IO11NB0F0	K12
IO11PB0F0	J12
IO12NB0F1	G11
IO12PB0F1	H11
IO13NB0F1	G12
IO13PB0F1	H12
IO14NB0F1	A7
IO14PB0F1	B7
IO15NB0F1	H13
IO15PB0F1	J13
IO16NB0F1	C9
IO16PB0F1	D9

FG1152	
AX2000 Function	Pin Number
IO17NB0F1	F12
IO17PB0F1	F11
IO18NB0F1	E11
IO18PB0F1	E10
IO19NB0F1	F13
IO19PB0F1	G13
IO20NB0F1	A10
IO20PB0F1	A9
IO21NB0F1	K14
IO21PB0F1	K13
IO22NB0F2	B11
IO22PB0F2	B10
IO23NB0F2	C12
IO23PB0F2	C11
IO24NB0F2	A12
IO24PB0F2	A11
IO25NB0F2	H14
IO25PB0F2	J14
IO26NB0F2	D13
IO26PB0F2	D12
IO27NB0F2	F14
IO27PB0F2	G14
IO28NB0F2	E14
IO28PB0F2	E13
IO29NB0F2	B13
IO29PB0F2	B12
IO30NB0F2	C14
IO30PB0F2	C13
IO31NB0F2	H15
IO31PB0F2	J15
IO32NB0F2	A14
IO32PB0F2	B14
IO33NB0F2	K15
IO33PB0F2	L15
IO34NB0F3	D15

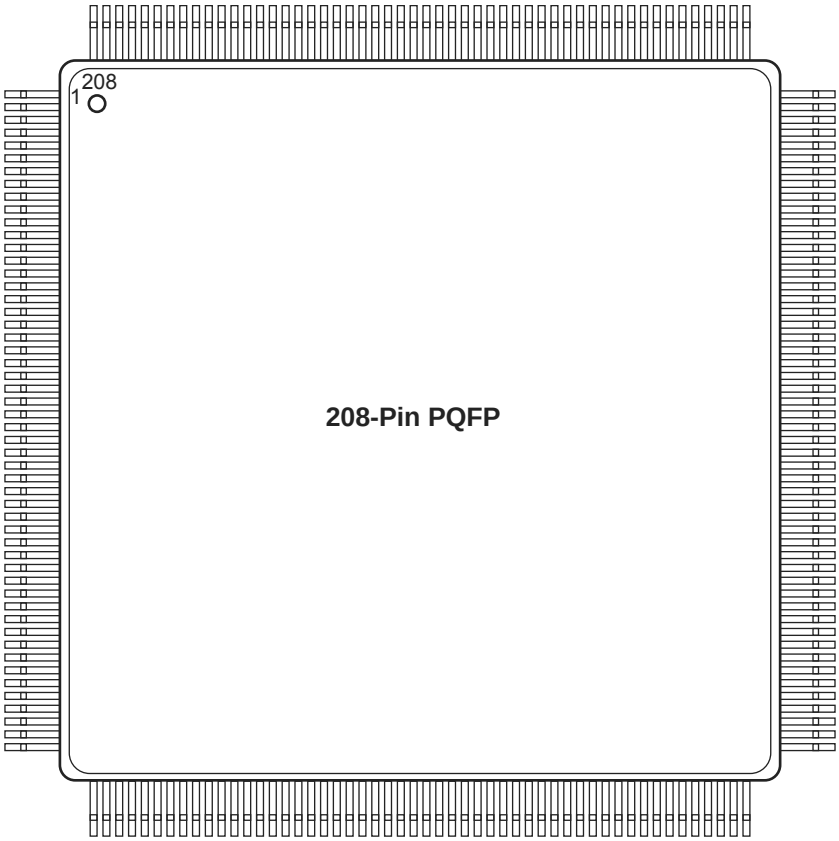
FG1152	
AX2000 Function	Pin Number
IO34PB0F3	D14
IO35NB0F3	A15
IO35PB0F3	B15
IO36NB0F3	B16
IO36PB0F3	A16
IO37NB0F3	G16
IO37PB0F3	G15
IO38NB0F3	D16
IO38PB0F3	C16
IO39NB0F3	K16
IO39PB0F3	L16
IO40NB0F3	D17
IO40PB0F3	C17
IO41NB0F3/HCLKAN	E16
IO41PB0F3/HCLKAP	F16
IO42NB0F3/HCLKBN	G17
IO42PB0F3/HCLKBP	F17
Bank 1	
IO43NB1F4/HCLKCN	G19
IO43PB1F4/HCLKCP	G18
IO44NB1F4/HCLKDN	E19
IO44PB1F4/HCLKDP	F19
IO45NB1F4	C18
IO45PB1F4	D18
IO46NB1F4	A18
IO46PB1F4	B18
IO47NB1F4	K19
IO47PB1F4	L19
IO48NB1F4	C19
IO48PB1F4	D19
IO49NB1F4	K20
IO49PB1F4	L20
IO50NB1F4	A19
IO50PB1F4	B19
IO51NB1F4	H20

FG1152	
AX2000 Function	Pin Number
GND	N1
GND	N13
GND	N22
GND	N34
GND	P14
GND	P15
GND	P16
GND	P17
GND	P18
GND	P19
GND	P20
GND	P21
GND	R14
GND	R15
GND	R16
GND	R17
GND	R18
GND	R19
GND	R20
GND	R21
GND	R3
GND	R32
GND	T14
GND	T15
GND	T16
GND	T17
GND	T18
GND	T19
GND	T20
GND	T21
GND	U14
GND	U15
GND	U16
GND	U17
GND	U18

FG1152	
AX2000 Function	Pin Number
GND	U19
GND	U20
GND	U21
GND	U30
GND	U5
GND	V14
GND	V15
GND	V16
GND	V17
GND	V18
GND	V19
GND	V20
GND	V21
GND	V30
GND	V5
GND	W14
GND	W15
GND	W16
GND	W17
GND	W18
GND	W19
GND	W20
GND	W21
GND	Y14
GND	Y15
GND	Y16
GND	Y17
GND	Y18
GND	Y19
GND	Y20
GND	Y21
GND	Y3
GND	Y32
GND/LP	G6
NC	A17

FG1152	
AX2000 Function	Pin Number
NC	A26
NC	AB2
NC	AB33
NC	AC34
NC	AD3
NC	AD34
NC	AE31
NC	AE33
NC	AE34
NC	AF1
NC	AF34
NC	AG2
NC	AG4
NC	AH1
NC	AH2
NC	AH31
NC	AH32
NC	AH34
NC	AJ1
NC	AJ2
NC	AJ3
NC	AJ31
NC	AJ32
NC	AJ33
NC	AJ34
NC	AJ4
NC	AL29
NC	AM19
NC	AM7
NC	AN13
NC	AN17
NC	AN25
NC	AN27
NC	AN8
NC	AP17

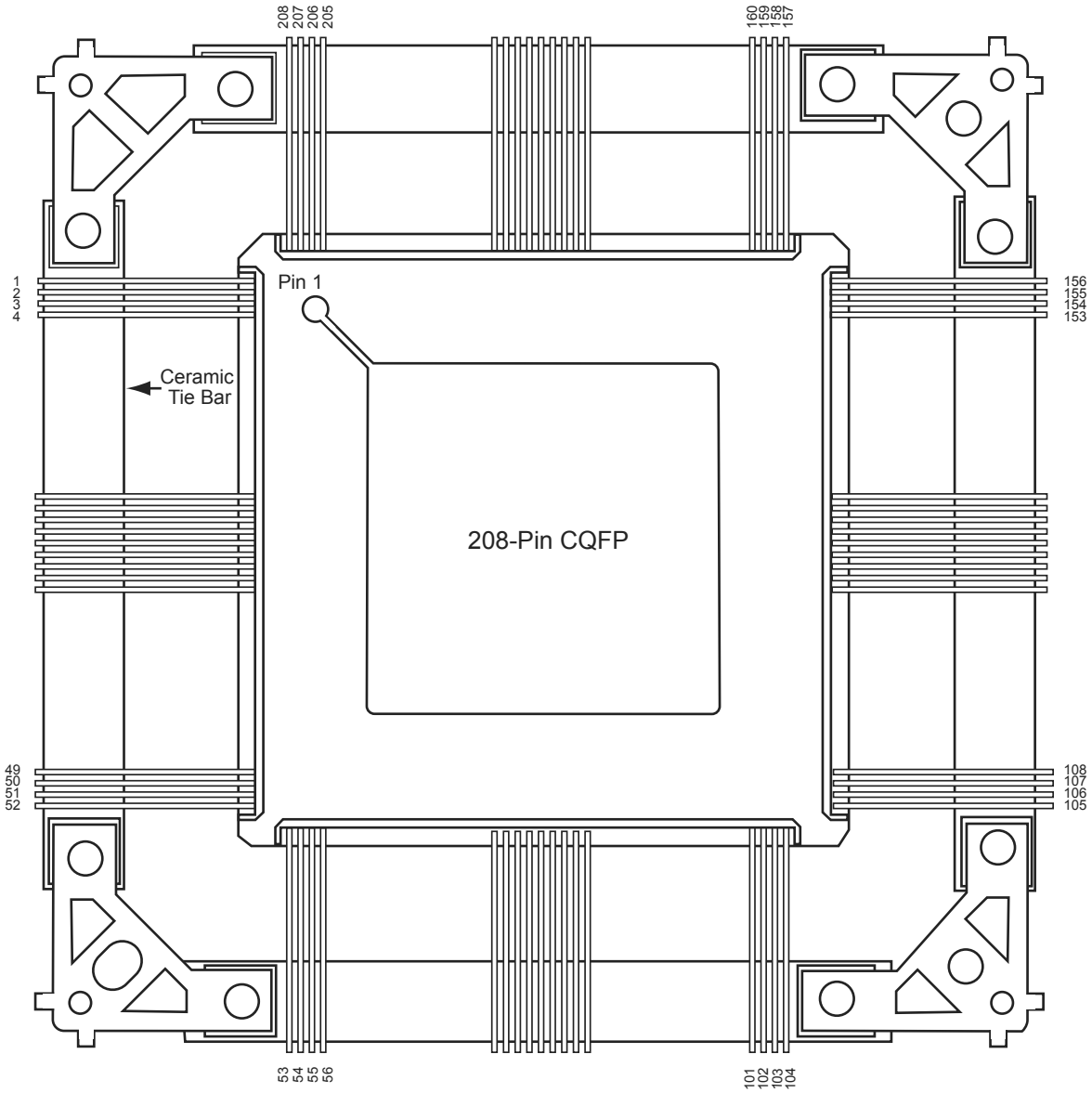
PQ208



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

CQ208



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CG624	
AX1000 Function	**Pin Number**
VCCA	U17
VCCA	U9
VCCA	Y4
VCCDA	A12
VCCDA	AA13
VCCDA	AA15
VCCDA	AA7
VCCDA	AC11
VCCDA	AD11
VCCDA	AE17
VCCDA	B15
VCCDA	C15
VCCDA	C6
VCCDA	D13
VCCDA	E13
VCCDA	E19
VCCDA	G5
VCCDA	N21
VCCDA	N5
VCCDA	W21
VCCIB0	A3
VCCIB0	B3
VCCIB0	C4
VCCIB0	D5
VCCIB0	J10
VCCIB0	J11
VCCIB0	K12
VCCIB1	A23
VCCIB1	B23
VCCIB1	C22
VCCIB1	D21
VCCIB1	J15
VCCIB1	J16
VCCIB1	K14
VCCIB2	C24
VCCIB2	C25

CG624	
AX1000 Function	**Pin Number**
VCCIB2	D23
VCCIB2	E22
VCCIB2	K17
VCCIB2	L17
VCCIB2	M16
VCCIB3	AA22
VCCIB3	AB23
VCCIB3	AC24
VCCIB3	AC25
VCCIB3	P16
VCCIB3	R17
VCCIB3	T17
VCCIB4	AB21
VCCIB4	AC22
VCCIB4	AD23
VCCIB4	AE23
VCCIB4	T14
VCCIB4	U15
VCCIB4	U16
VCCIB5	AB5
VCCIB5	AC4
VCCIB5	AD3
VCCIB5	AE3
VCCIB5	T12
VCCIB5	U10
VCCIB5	U11
VCCIB6	AA4
VCCIB6	AB3
VCCIB6	AC1
VCCIB6	AC2
VCCIB6	P10
VCCIB6	R9
VCCIB6	T9
VCCIB7	C1
VCCIB7	C2
VCCIB7	D3

CG624	
AX1000 Function	**Pin Number**
VCCIB7	E4
VCCIB7	K9
VCCIB7	L9
VCCIB7	M10
VCCPLA	E12
VCCPLB	J12
VCCPLC	E14
VCCPLD	H14
VCCPLE	Y14
VCCPLF	U14
VCCPLG	Y12
VCCPLH	U12
VCOMPLA	F12
VCOMPLB	H12
VCOMPLC	F14
VCOMPLD	J14
VCOMPLE	AA14
VCOMPLF	V14
VCOMPLG	AA12
VCOMPLH	V12
VPUMP	E20

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